



Amendment Under 37 C.F.R. §1.116
Expedited Handling Procedure
Box AF
Group Art Unit: 2503

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re patent application of

K. Kata et al. ✓

Serial No.: 08/533,207

Group Art Unit: 2503

Filed: September 25, 1995

Examiner: M. Prenty ✓

For: PROCESS FOR MANUFACTURING SEMICONDUCTOR DEVICE
AND SEMICONDUCTOR WAFER

Assistant Commissioner for Patents
Box AF
Washington, D.C. 20231

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GROUP 2500

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AMENDMENT UNDER 37 C.F.R. §1.116

Sir:

In response to the Office Action mailed September 23, 1997, please
amend the above-identified application as follows:

IN THE SPECIFICATION:

✓ On page 8, line 28, after "chips" delete ", chip electrodes formed on the
opposite side of the semiconductor chips and interconnection layers connecting
the chip electrodes and the bump electrodes, wherein the chip electrodes are not
located directly across the chip from the bump electrodes".

IN THE CLAIMS:

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- 1 5. (Three Times Amended) A semiconductor wafer having a plurality of
2 semiconductor chips, comprising bump electrodes simultaneously formed into a

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